

IN THE CLAIMS

Claims 16-25 were previously canceled without prejudice as non-elected claims.

Claims 2-5 and 14 were previously amended.

Please amend claims 1, 11, and 14-15.

Please enter the pending claims as follows:

1. (Currently Amended) A device having Input/Output (I/O) connections to a package or board comprising :
 a bond pad [pads],
 a BLM disposed over said bond pad [pads], said BLM split into
 [having] two or more segments, said segments in close proximity to each
 other, said segments separated by a gap, and
 a bump disposed over said segments.
2. (Previously Amended) The device of claim 1 wherein said bump comprises a Lead-Tin (Pb-Sn) solder.
3. (Previously Amended) The device of claim 1 wherein said bump is free of Lead (Pb).

4. (Previously Amended) The device of claim 1 wherein said bump comprises a Tin-Silver-Copper (Sn-Ag-Cu) ternary alloy.
5. (Previously Amended) The device of claim 1 wherein said bump comprises an Electrically Conductive Adhesive (ECA).
6. (Original) The device of claim 1 wherein said BLM provides a diffusion barrier to metals.
7. (Original) The device of claim 1 wherein said BLM comprises a lower layer and an upper layer.
8. (Original) The device of claim 7 wherein said lower layer comprises Titanium (Ti) with a thickness of about 200 to 1500 Angstroms.
9. (Original) The device of claim 7 wherein said upper layer comprises Nickel-Vanadium (Ni-V) with a thickness of about 1000 to 8000 Angstroms.
10. (Original) The device of claim 1 wherein said segments comprise a substantially polygonal layout.

11. (Currently Amended) The device of claim 1 further comprising vias, wherein each of said segments [a segment] is electrically connected to two or more of said vias.
12. (Original) The device of claim 11, wherein said vias are laterally offset from a center of said bump to which they are is electrically connected.
13. (Original) The device of claim 11 wherein said vias comprise a substantially polygonal layout.
14. (Currently Amended) The device of claim 1 [4], further comprising another bond pad, wherein each of said segments is electrically connected to [two or more of] said bond pad and said another bond pad [pads].
15. (Currently Amended) The device of claim 14 wherein said bond pad and said another bond pad [pads] are laterally offset from a center of said bump to which they are electrically connected.
- 16.-25. (Canceled)
26. (Original) A device having I/O connections to a package or board comprising :
a bond pad, said bond pad having two or more segments, and

a wire lead attached to said segments.

27. (Original) The device of claim 26 further comprising vias, wherein a segment is electrically connected to two or more of said vias.

28. (Original) The device of claim 26 further comprising lines, wherein a segment is electrically connected to two or more of said lines.